

GP1FMV51RK0F

Fiber Optic Receiver
Square connector
Compact (without mounting hole)
With shutter



■Description

GP1FMV51RK0F employs an OPIC device that integrates a photodiode and signal processing circuit onto a single chip, and the output is at TTL levels.

■Features

1. Fiber optic receiver
(Transmitter : **GP1FMV51TK0F**)
2. Square connector (JEITA RC-5720B)
3. Compact (without mounting hole)
4. With shutter function
5. Supply voltage : 5 V
6. Transfer rate : 13.2 Mb/s

■Agency approvals/Compliance

1. Compliant with JEITA RC-5720B and CP1201
2. Compliant with RoHS directive (2002/95/EC)

■Applications

AV equipment
(DVD, CD, MD players etc.)

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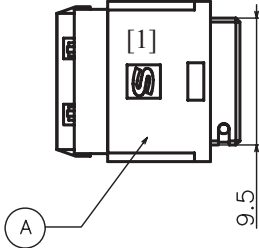
Sheet No.: E2-A01001EN

Date Dec.01.2006

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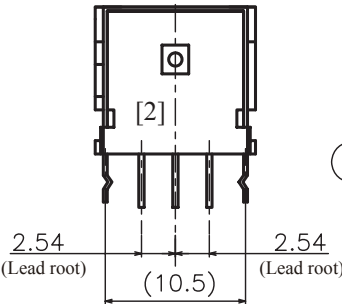
Outline Dimensions

(Unit: mm)

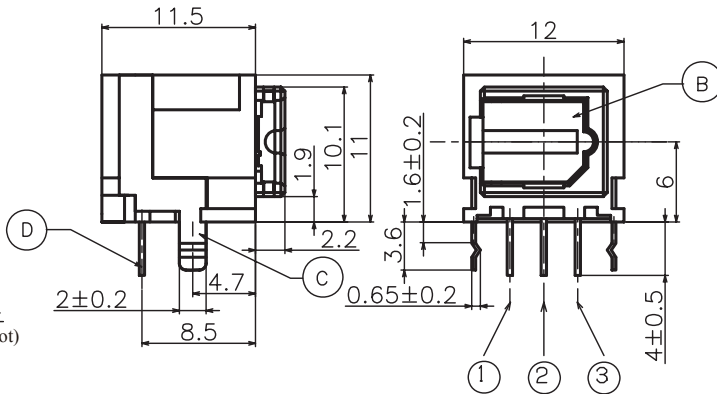


(A)

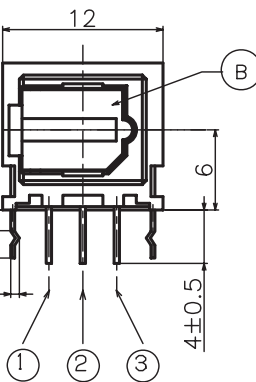
Symbol	Description	Material
A	Holder	PBT (Color : Black)
B	Shutter	PBT (Color : Black)
C	Fixing pin	SPCC (Lead free plating)
D	Lead pin	Cu Alloy (SnCu plating)



(2)

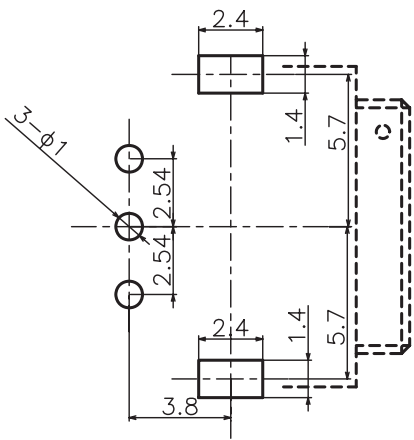


(D)

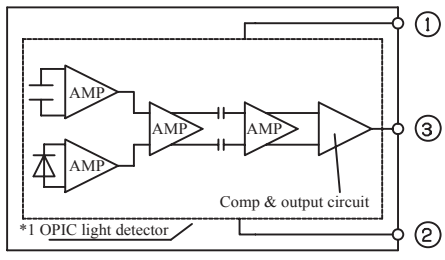


(B)

Example of mounting drawing form solder side.
PCB thickness t = 1.6 mm
Unspecified tolerance ± 0.1

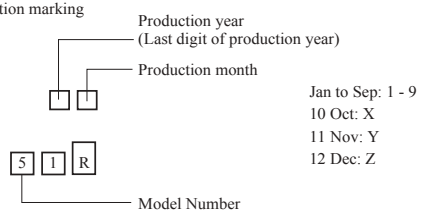


Internal equivalent circuit



*1 OPIC is a registered trade mark of Sharp (Material : Silicon)

[2] Portion marking



Production year (Last digit of production year)
Production month
Model Number

Jan to Sep: 1 - 9
10 Oct: X
11 Nov: Y
12 Dec: Z

Pin arrangement

① V_{cc}
② GND
③ V_{out}

- 1) The connector joint area complies with the square connector JEITA RC-5720B
- 2) [1] portion : "S" mark, [2] portion : Model No. and date code shall be indicated.
- 3) Unspecified tolerance shall be ± 0.3.
- 4) Since there are other products which has a different fixing pin shape, please make sure to confirm reference mounting drawing for this device.
- 5) Dimensions in parenthesis are shown for reference.

Product mass : approx. 2 g

■ Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit	Remark
Supply voltage	V_{CC}	-0.5 to +7.0	V	
Operating temperature	T_{opr}	-20 to +70	°C	
Storage temperature	T_{stg}	-30 to +80	°C	
Soldering temperature *1	T_{sol}	260	°C	6 s or less/time up to 2 times.
		380	°C	4 s or less/time up to 1 time. Soldering by hand at each terminal. *2
Output current	I_{oH}	2	mA	Source current
	I_{oL}	10	mA	Sink current

*1 Solder at a position more than 1.6 mm away from the base of the lead terminal. Reflow is not available.

*2 Do not contact top of soldering iron to lead terminal directly.

■ Recommended Operating Conditions

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Remark
Supply voltage	V_{CC}	4.75	5.0	5.25	V	
Operating transfer rate	T	0.1	-	13.2	Mb/s	Notes (1), (2)
Receiver input optical power level	P_C	-24.0	-	-14.5	dBm	Peak optical output

Notes

(1) This operating transfer rate shall be a specification when NRZ, duty 50 % of continuous “0101…” signal is transferred.

(2) The output (H/L Level) of this product are not fixed constantly when it receives the modulating light (including DC light, no input light) less than 0.1 Mb/s.

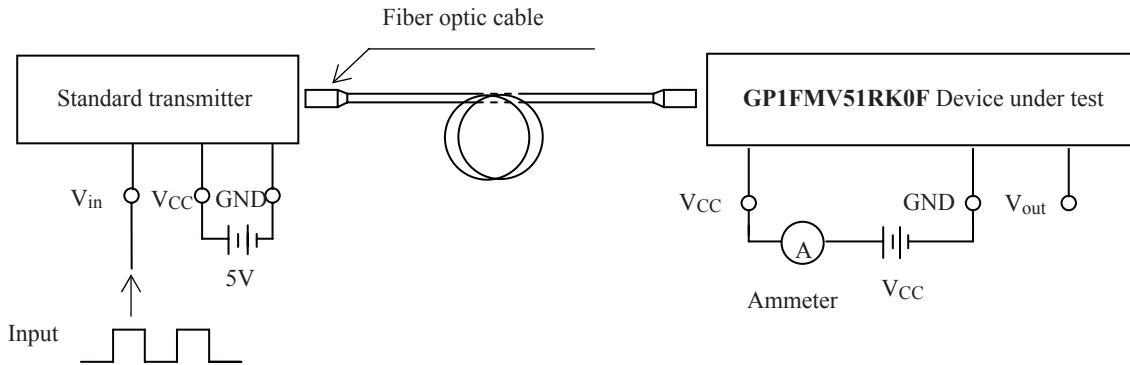
■ Electro-optical Characteristics

($T_a = 25\text{ °C}$, $V_{CC} = 5\text{ V}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Peak sensitivity wavelength	λ_p		-	700	-	nm
Supply current	I_{CC}	Measurement method refer to Fig. 1	-	16	25	mA
High level output voltage	V_{oH}	Measurement method refer to Fig. 2, 3	2.7	3.5	-	V
Low level output voltage	V_{oL}		-	0.35	0.5	V
Rise time	t_r		-	15	23	ns
Fall time	t_f		-	7	15	ns
L → H delay time	t_{pLH}		-	-	180	ns
H → L delay time	t_{pHL}		-	-	180	ns
Pulse width distortion	Δt_w		-20	-	+20	ns
Jitter	Δt_j		Measurement method refer to Fig. 4, 5, PC = -14.5 dBm	-	1	15
		Measurement method refer to Fig. 4, 5, PC = -24 dBm	-	-	15	ns

■ **Measurement Method**

Fig. 1 Supply Current



Input conditions		Judgment method
Supply voltage	$V_{CC} = 5.0 \text{ V}$	Measured on an ammeter (DC mean amperage)
Optical fiber coupling light output	$P_C = -14.5 \text{ dBm}$	
Standard transmitter input signal	13.2 Mb/s NRZ, Duty 50 % or 6.6 Mb/s bi-phase mark PRBS signal	

Fig. 2 Output Voltage and Pulse Response

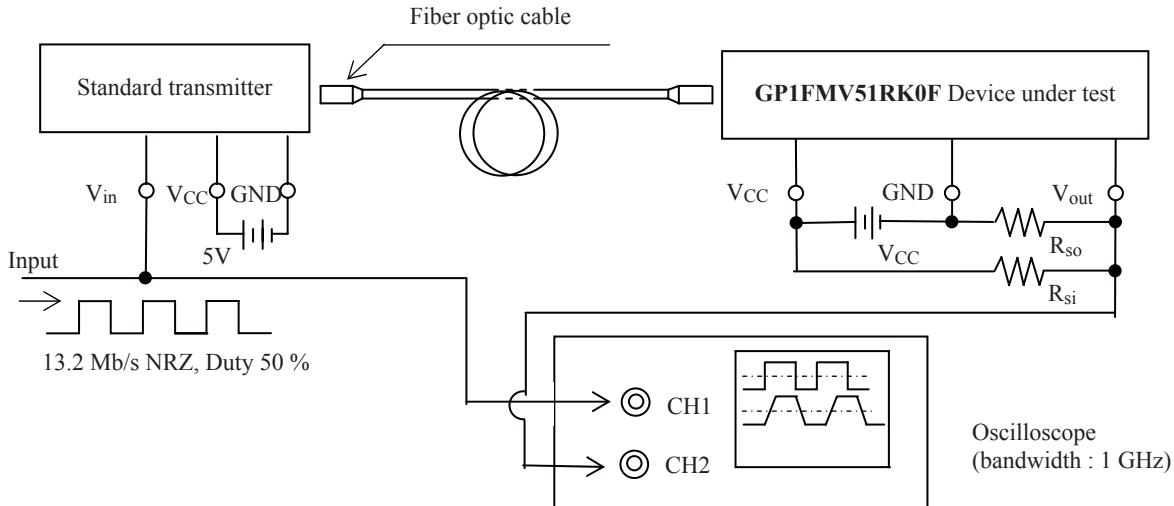
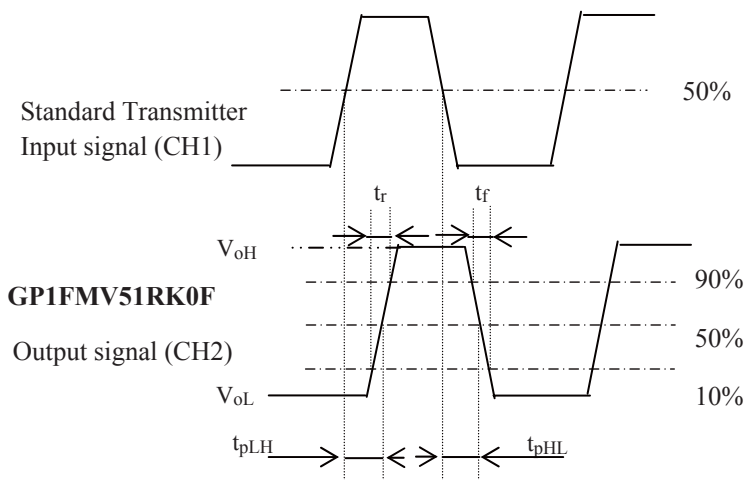


Fig. 3 Input and Output Signal



Notes

- (1) $V_{CC} = 5.0V$ (State of operating)
- (2) The fiber coupling light output set at -14.5 dBm or -24.0 dBm .
- (3) The probe for the oscilloscope must be more than $1 \text{ M}\Omega$ and less than 10 pF .
- (4) R_{Si} , R_{So} : Standard load resistor (R_{Si} : $3.3 \text{ k}\Omega$, R_{So} : $2.2 \text{ k}\Omega$)
- (5) The output (H/L level) of this device are not fixed constantly when it receives the modulating light (including DC light, no input light) less than 0.1 Mb/s .

Fig. 4 Pulse Response and Jitter

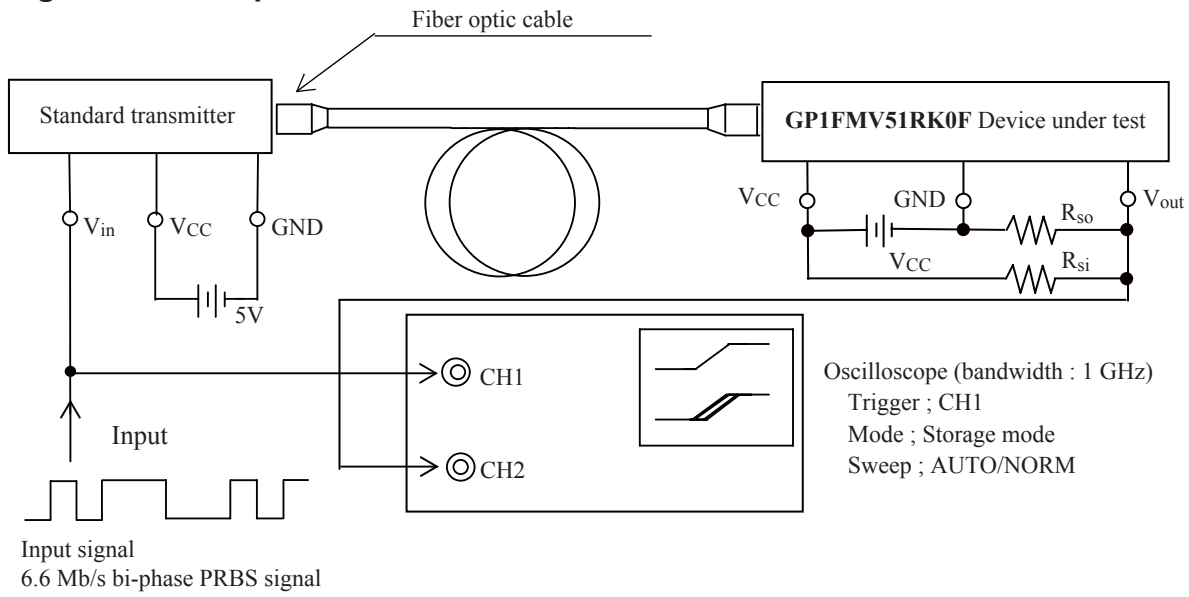
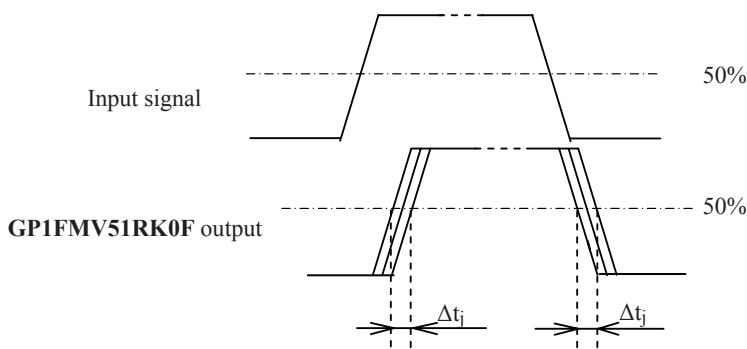


Fig. 5 Input Signal (6.6 Mb/s Bi-phase PRBS Signal)



Notes

- (1) The fiber coupling light output set at -14.5 dBm or -24.0 dBm.
- (2) R_{si}, R_{so}: Standard load resistor (R_{si}: 3.3 k Ω , R_{so}: 2.2 k Ω)
- (3) Set the oscilloscope to the storage mode and write time to 3 seconds.
Do not allow the brightness to be increased too much. The waveform would be distorted.
- (4) V_{CC} = 5.0 V (State of operating)
- (5) The probe for the oscilloscope must be more than 1 M Ω and less than 10 pF.

■Design and Production Notes**(1) Stabilization of power supply line**

Please put a by-pass capacitor (0.1 μ F) close to the device at least within 7 mm of the terminal.
Please also put a 4.7 μ F capacitor across the power supply line nearby.

(2) Soldering condition

Solder at the condition within the absolute maximum ratings in this sheet. In case of using flow soldering, please make sure of the conditions of process at the flow equipment. Also, do not use reflow soldering. In case of soldering by hand, do not contact top of soldering iron to lead terminal directly. (Solder at a position more than 1.6 mm away from the base of the lead terminal.)

(3) About getting dirt and dust in the connector coupling portion

In case dirt or dust comes into the connector coupling portion, please use a blower to take it off.
Any rigid rod-like object must not be inserted since into the coupling portion.
The internal device might be damaged, resulting deteriorated characteristics.

(4) Cleaning

Do not immerse for cleaning. The solvent would get into the connector coupling portion resulting deteriorated characteristics. Should it be necessary to remove the flux, please use one of the following solvents only to be applied with a brush.
Solvent : Isopropyl alcohol, Methyl alcohol

(5) Ground during assembling

The human body and the soldering iron must be grounded against the static breakdown of the device during assembling.
Please avoid touching the device terminals as much as possible before assembling.

(6) Assembly of the device

Please fix this device with soldering the metal sheet in PCB. And do not lay the PCB pattern or land for wiring where the metal sheet contacts PCB.

(7) Input signal

This product is designed intentionally based upon the signal transmission which is defined by the digital audio interface standard ; CP1201. When a signal out of JEITA standard CP-1201 is inputted to this device, there might be a case that this device can not receive a signal correctly from transmitting unit.

(8) Fixing pin

Since there are other products which has a different fixing pin shape, please make sure to confirm reference mounting drawing for this device.

(9) Damage to connector coupling portion

Please do not stress the connector coupling portion excessively since there might be a case that the shutter can't operate normally.

(10) About getting the flux into connector coupling portion

Please avoid getting a flux into connector coupling portion of this device, because there might be a case that the characteristics deteriorate the shutter can't operate normally.

● Presence of ODC etc.

This product shall not contain the following materials.

And they are not used in the production process for this product.

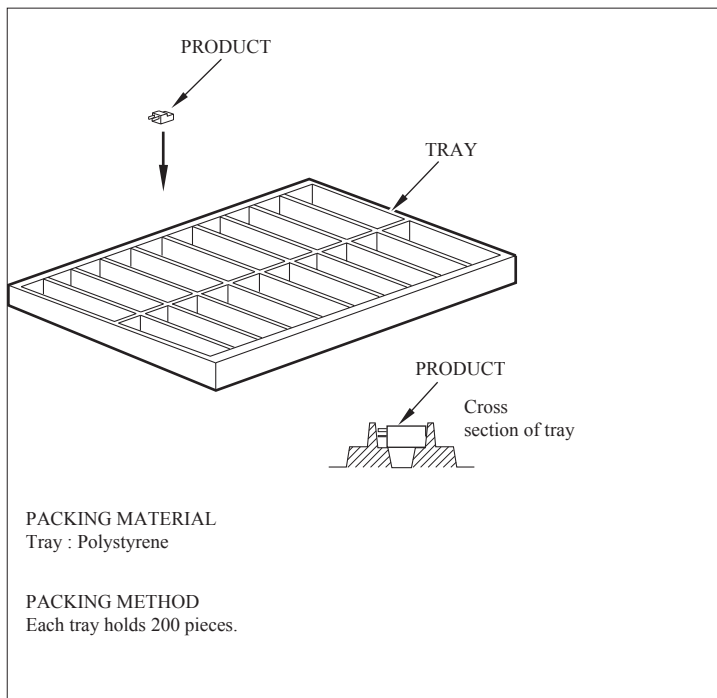
Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBB and PBDE are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

- Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).

■ Packing Specifications



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- Test and measurement equipment
- Industrial control
- Audio visual equipment
- Consumer electronics

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- Alarm equipment
- Various safety devices, etc.

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